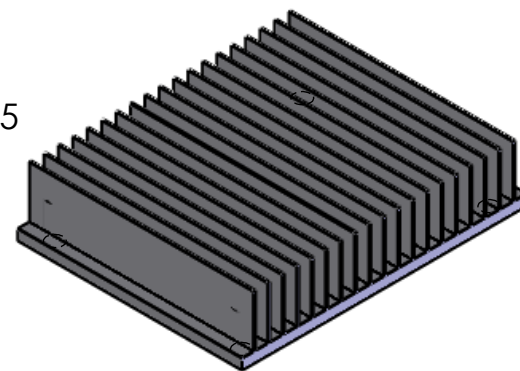
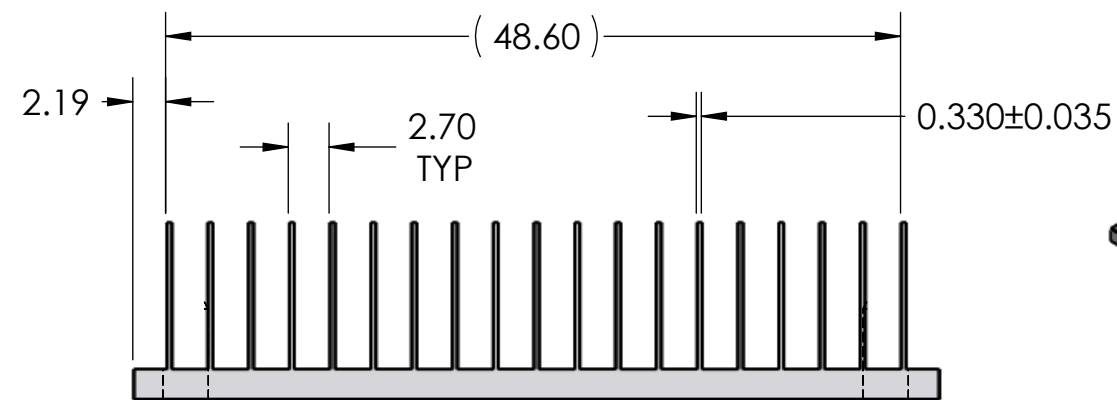
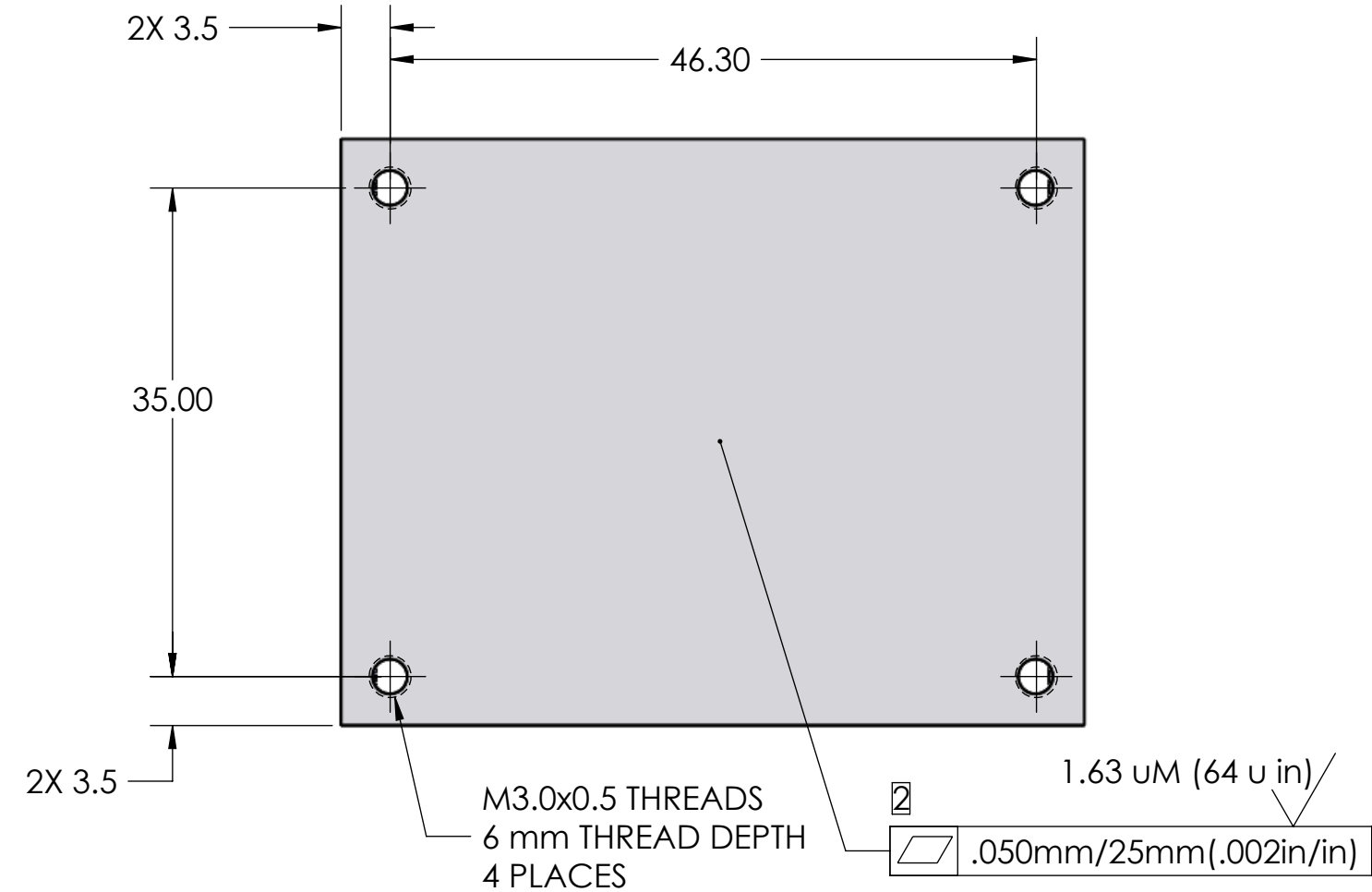
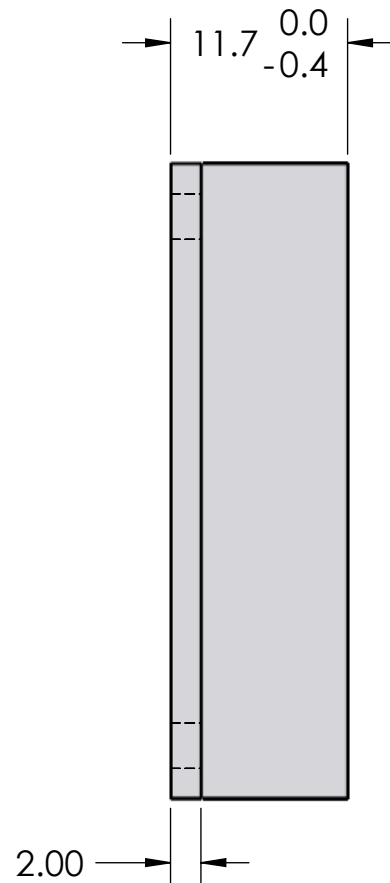
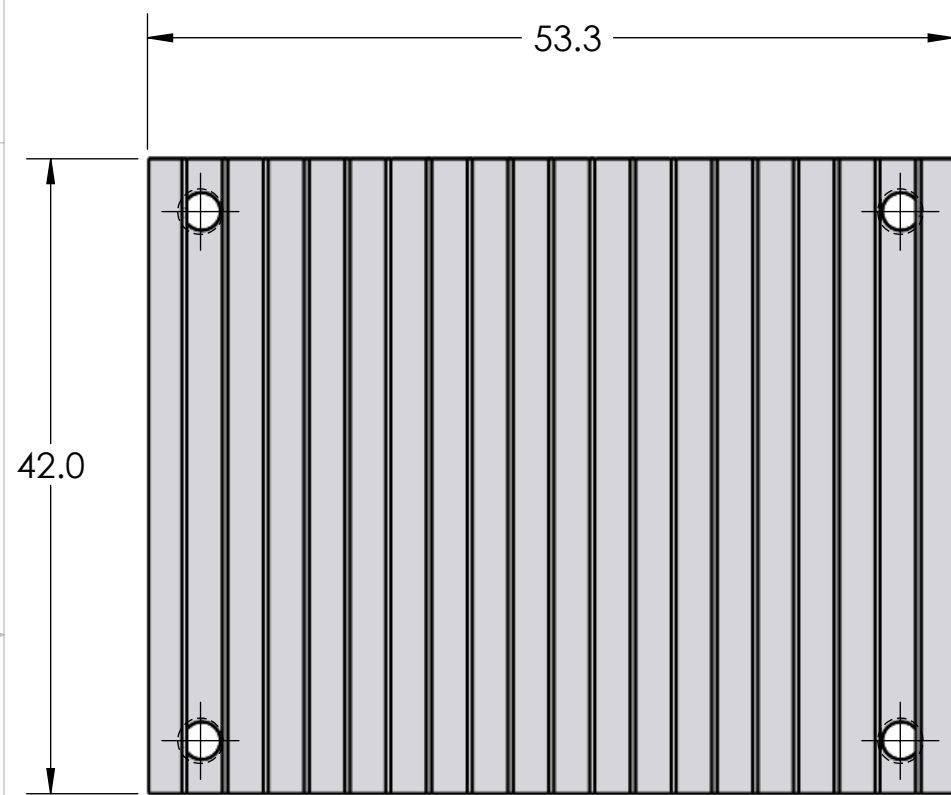


REV	DESCRIPTION	BY	APR	DATE
A01	INITIAL RELEASE	CHC	BLN	2009-10-11

NOTES:

- REFER TO DATASHEET FOR ADDITIONAL INFORMATION.
- CHIP MOUNTING SURFACE.
- APPROXIMATE MASS VALUES: 20g. (Al) , 65g. (Cu).



ANGLED VIEW FOR REFERENCE ONLY

PARTS COVERED		MATERIAL	
HSCCS-CALCL-001		ALUMINUM 6063 OR 1100 SERIES	
HSCCS-CCUCL-001		COPPER 101 OR 110	
<b>UNLESS OTHERWISE SPECIFIED:</b>		NAME	DATE
-ALL DIMENSIONS IN MILLIMETERS		DRAWN CHC	11OCT09
-DRAFT ANGLES TO BE 3 DEGREES		CHECKED DNG	11OCT09
-DIMENSIONS INCLUDE PLATING		ENG APPR. DNG	11OCT09
TOLERANCES: .X: ± 0.2			
.XX: ± 0.1			
ANGLES: ±0.5°			
SIZE	MATERIAL	THIRD ANGLE PROJECTION	
<b>B</b>	N/A		
FINISH	N/A		
DO NOT SCALE DRAWING		TITLE: HEAT SINK, LOW PROFILE CHIP COOLER	
		DWG. NO. MKT-HSCCS-001	REV A01
		SCALE: 1:1	SHEET 1 OF 1

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